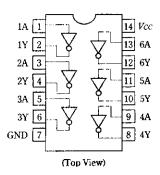
■ PIN ARRANGEMENT



M ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Ratings	Unit V	
Supply voltage	Vcc	7.0		
Input voltage	Vin	7.0	V	
Output voltage	Vout	30	V	
Operating temperature range	Topr	-20 ~ +75		
Storage temperature range	Tstg	65 ~ +150	°C	

RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
Supply voltage	Vcc	4.75	5.00	5.25	V
High level output voltage	Von	_		30	V
Low level output current	IOL	-	-	48	mA
Operating temperature range	Topr	-20	25	75	°C

■ ELECTRICAL CHARACTERISTICS (Ta = -20 ~ +75°C)

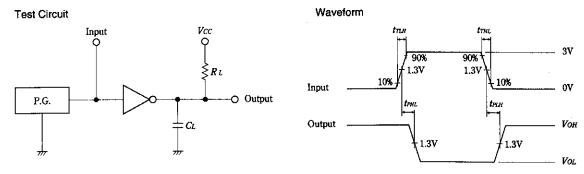
Item	Symbol	Test Conditions		min	typ*	max	Unit	
	VIH			1.10	2.0	_	_	V
Input voltage	VIL				-	_	0.8	V
Output voltage Vol.		17. 10077	/, <i>Viн</i> = 2V	<i>IoL</i> = 24mA		-	0.4	V
	VOL	<i>Vcc</i> = 4.75V,		<i>Iot</i> = 48mA	-		0.5	V
	Iін	$V_{CC} = 5.25V$	$V_{I} = 2.7V$			_	20	μA
Input current III	IIL	Vcc = 5.25V,	$V_{I} = 0.4 \text{V}$		_	-	-0.4	mA
	II	Vcc = 5.25V,	V1 = 7V		_	-	0.1	mA
Output current	Іон	Vcc = 4.75V,	$V_{IL} = 0.8V$,	<i>VoH</i> = 30V	-	_	250	μA
Supply current Icch	Іссн	Vcc = 5.25V			T -	23	48	mA
	ICCL	Vcc = 5.25V			_	21	51	mA
Input clamp voltage	Vik	$V_{CC} = 4.75 \text{V},$	IIN = -18mA		_	_	-1.5	V

^{*}Vcc = 5V, Ta = 25°C

■ SWITCHING CHARACTERISTICS (Vcc = 5V, Ta = 25°C)

Item	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time tplh tphl.	t _{PLH}		-	10	15	ns
		$CL = 15 \text{pF}, RL = 110 \Omega$	_	15	23	ns

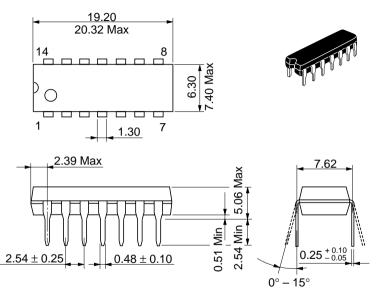
■ TESTING METHOD



Notes) 1. Input pulse: PRR = 1MHz, duty cycle 50%, Zout = 50Ω, trun≤15ns. trnu≤6ns

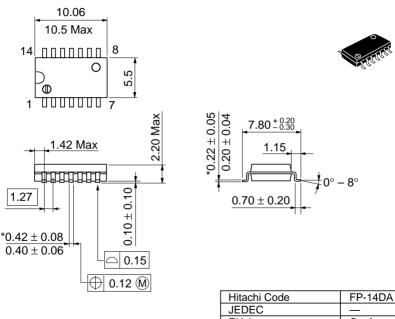
- 2. CL includes probe and jig capacitance.
- 3. All diodes are 1S2074(H)

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm



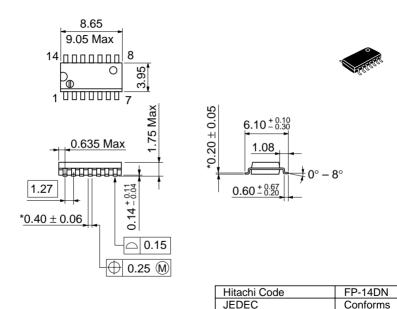
*Dimension including the plating thickness
Base material dimension

*Dimension including the plating thickness

Base material dimension

Weight (reference value) 0.23 g

Unit: mm



EIAJ

Weight (reference value)

Conforms

0.13 g

*Pd plating

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